



## **PRESS RELEASE**

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FOR IMMEDIATE RELEASE  
July 25, 2022

### **TechSearch International Examines High-Performance Package Options and Provides an Update on the Build-up Substrate Shortage**

TechSearch International's latest analysis describes high-performance package options with an update on TSMC's new offerings, including the latest organics CoWoS® versions. New high-end product examples using fan-out on substrate are discussed. Features of the build-up substrates supporting redistribution layer (RDL) structures are provided. Applications for high-performance wafer-to-wafer hybrid bonding are also described. Trends in integrated photonics packaging are discussed, including the use of fan-out options.

The report includes OSAT financials and examines economic trends impacting the industry. The past two years saw phenomenal growth in shipments of smartphones and PCs. Reduced demand for smartphones and PCs this year is changing package demand. High-performance and mid-range Samsung smartphones are examined to determine package usage.

TechSearch International analyzes changes in the gap between manufacturing demand and capacity for build-up substrates. Lower demand for PCs is easing the shortage this year, but demand continues to increase for the more complex, more expensive FC-BGA substrates. Examples of substrate features are included. IC package substrate design rules for major suppliers are provided in the report.

The latest Advanced Packaging Update is an 89-page report with full references and an accompanying set of 43 PowerPoint slides.

TechSearch International, Inc., founded in 1987, is a market research leader specializing in technology trends in microelectronics packaging and assembly. Multi- and single-client services encompass technology licensing, strategic planning, and market and technology analysis. TechSearch International professionals have an extensive network of more than 22,000 contacts in North America, Asia, and Europe. For more information, contact TechSearch at tel: 512-372-8887 or see [www.techsearchinc.com](http://www.techsearchinc.com). Follow us on twitter @Jan\_TechSearch and on LinkedIn.